

## **AMENDMENTS TO THE CLAIMS**

Claims 1-9 (Canceled)

10. (New) An analog resistive-film type thin-frame touch panel, comprising:

a lower-side electrode member having a lower-side transparent electrode on a part of a top face of a lower-side transparent insulating base member, a pair of lower-side bus bars disposed on two parallel sides of the lower-side transparent electrode, and lower-side external terminal connection portions disposed on a portion other than the lower-side transparent electrode and connected to the lower-side bus bars; and

an upper-side electrode member having an upper-side transparent electrode on a part of a bottom face of an upper-side transparent insulating base member having flexibility, a pair of upper-side bus bars disposed on two parallel sides of the upper-side transparent electrode, and upper-side external terminal connection portions disposed on a portion other than the upper-side transparent electrode and connected to the upper-side bus bars,

the lower-side electrode member and the upper-side electrode member being disposed facing each other via an insulative spacer in such a way that the upper-side bus bars and the lower-side bus bars are arranged in a square pattern, and being bonded at peripheral portions, wherein

the lower-side bus bars are formed by metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$  while the upper-side bus bars are formed by metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ , and in each of the upper-side electrode member and the lower-side electrode member, the metal thin wires are respectively fixed onto the upper-side transparent insulating base member and the lower-side transparent insulating base member through a conductive past.

11. (New) The thin-frame touch panel as defined in Claim 10, wherein

the lower-side electrode member further has lower-side routing circuits disposed on the portion other than the lower-side transparent electrode, for connecting the lower-side bus bars and the lower-side external terminal connection portions,

the upper-side electrode member further has upper-side routing circuits disposed on the portion other than the upper-side transparent electrode, for connecting the upper-side bus bars and the upper-side external terminal connection portions, and

the lower-side routing circuits are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$  and the upper-side routing circuits are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ .

12. (New) The thin-frame touch panel as defined in Claim 11, wherein the metal thin wires constituting each of the lower-side routing circuits and the upper-side routing circuits are extended to outsides of the lower-side electrode member and the upper-side electrode member to constitute the lower-side external terminal connection portions and the upper-side external terminal connection portions.

13. (New) The thin-frame touch panel as defined in Claim 10, wherein the lower-side bus bars and the lower-side external terminal connection portions are directly connected and the lower-side bus bars and the lower-side external terminal connection portions are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ , while the upper-side bus bars and the upper-side external terminal connection portions are directly connected and the upper-side bus bars and the upper-side external terminal connection portions are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ , and the metal thin wires of the upper-side external terminal connection portions and the metal thin wires of the lower-side external terminal connection portions are extended to outsides of a region where the lower-side electrode member and the upper-side electrode member are bonded to each other.

14. (New) The thin-frame touch panel as defined in Claim 10, wherein in the upper-side electrode member, the metal thin wire are fixed onto the upper-side transparent insulating base member via a conductive paste and in the lower-side electrode member, the metal thin wires are fixed onto the lower-side transparent insulating base member via a conductive paste.

15. (New) The thin-frame touch panel as defined in Claim 10, wherein in the upper-side electrode member, the metal thin wires are covered with a conductive paste and fixed onto the upper-side transparent insulating base member and in the lower-side electrode member, the metal thin wires are covered with a conductive paste and fixed onto the lower-side transparent insulating base member.

16. (New) The thin-frame touch panel as defined in Claim 15, wherein a lower-side covering layer formed by being covered with the conductive paste in at least either one of a bend portion of the lower-side routing circuit and the lower-side bus bar in the lower-side electrode member has a width 2 to 5 times larger than a diameter of the metal thin wire in the lower-side electrode member, and a lower-side covering layer formed by being covered with the conductive paste in other portions has a width 1 to 5 times larger than the diameter of the metal thin wire in the lower-side electrode member, while an upper-side covering layer formed by being covered with the conductive paste in at least either one of a bend portion of the upper-side routing circuits and the upper-side bus bars in the upper-side electrode member has a width 3 to 5 times larger than a diameter of the metal thin wire in the upper-side electrode member, and an upper-side covering layer formed by being covered with the conductive paste in other portions has a width 2 to 5 times larger than the diameter of the metal thin wire in the upper-side electrode member.

17. (New) The thin-frame touch panel as defined in Claim 10, wherein a specific resistance value of the metal thin wire is  $20 \times 10^{-6} \Omega \cdot \text{cm}$  or less.

18. (New) The thin-frame touch panel as defined in Claim 17, wherein the metal thin wire on the transparent insulating base member and its periphery are covered with a conductive paste with a specific resistance value of  $1 \times 10^{-4} \Omega \cdot \text{cm}$  or less.

19. (New) The thin-frame touch panel as defined in Claim 10, wherein a thin-frame of the touch panel is an interconnection region in the upper-side transparent insulating base member and the

lower-side transparent insulating base member of the touch panel, in which the bus bars, the routing circuits, and the external terminal connection portions are formed at peripheries of the transparent insulating base members, the region being formed such that its thin-frame width size as seen from an external form thereof is 2 mm or lower at least on three sides.